

Feature:

- Antireflective Pb free silver paste
- High resistance member of the system Ag 3902 / Ag 3903

Benefits:

- Wide window of compatibility with several black enamels
- Superior substrate wetting
- High chemical durability

## PROCESSING CONDITIONS

**Printing:** 200 – 250 mesh screen and 0.4 mm minimum line width are recommended.

**Soldering:** 47% Sn, 40% Pb, 10% Bi, 3% Ag solder at 230°C.

**Shelf life:** 8 months @ 4°-10°C, 6 months @ 10-24°C

**Thinners:** Thinning is not recommended, the paste is optimized to the correct viscosity for screen printing. Use the Chimet 0202 IT/0201IT to replace solvent losses, by contacting the local Chimet technician

## TYPICAL PROPERTIES

**Metal content:**

Ag **65.0 %**

**Resistivity:**

**32 mΩ · μm**

**Viscosity:**

**40 – 60 Pa.s**

## STANDARD TEST CONDITIONS

**Viscosity test:**

Viscosimeter Brookfield DV II, Cylinder  $\varnothing = 4$  cm h = 7 cm, Spindle 7 R at 10 r.p.m. and 23.5 ( $\pm 0,5$ )°C.

**Resistance test:**

Circuit: 1000 x 1 mm  
Printing : 250 mesh  
Fired thickness: Taylor-Hobson profilometer

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